

# Octal D Flip-Flop with 3-State Outputs

## MC74AC574, MC74ACT574

The MC74AC574/74ACT574 is a high–speed, low power octal flip–flop with a buffered common Clock (CP) and a buffered common Output Enable ( $\overline{\rm OE}$ ). The information presented to the D inputs is stored in the flip–flops on the LOW–to–HIGH Clock (CP) transition.

The MC74AC574/74ACT574 is functionally identical to the MC74AC374/74ACT374 except for the pinouts.

#### **Features**

- Inputs and Outputs on Opposite Sides of Package Allowing Easy Interface with Microprocessors
- Useful as Input or Output Port for Microprocessors
- Functionally Identical to MC74AC374/74ACT374
- 3-State Outputs for Bus-Oriented Applications
- Outputs Source/Sink 24 mA
- 'ACT574 Has TTL Compatible Inputs
- Pb-Free Packages are Available

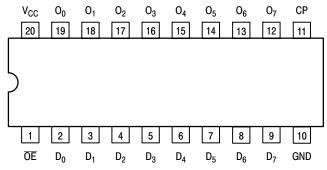


Figure 1. Pinout: 20-Lead Packages Conductors

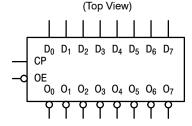


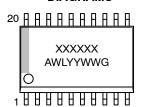
Figure 2. Logic Symbol

#### **PIN ASSIGNMENT**

PIN	FUNCTION				
D <sub>0</sub> -D <sub>7</sub>	Data Inputs				
СР	Clock Pulse Input				
ŌĒ	3-State Output Enable Input				
O <sub>0</sub> -O <sub>7</sub>	3-State Outputs				

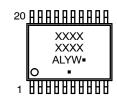
#### MARKING DIAGRAMS







TSSOP-20 DT SUFFIX CASE 948E



XXXXXX = Specific Device Code A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

#### **FUNCTIONAL DESCRIPTION**

The MC74AC574/74ACT574 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-state true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ( $\overline{OE}$ ) LOW, the contents of the eight flip-flops are available at the outputs. When  $\overline{OE}$  is HIGH, the outputs go to the high impedance state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops.

#### **FUNCTION TABLE**

	Inputs		Internal	Outputs	Function
ŌĒ	CP	D	Q	O <sub>n</sub>	runction
Н	Н	L	NC	Z	Hold
Н	Н	Н	NC	Z	Hold
Н	」	L	L	Z	Load
Н	」	Н	Н	Z	Load
L	」	L	L	L	Data Available
L	」	Н	Н	Н	Data Available
L	Н	L	NC	NC	No Change in Data
L	Н	Н	NC	NC	No Change in Data

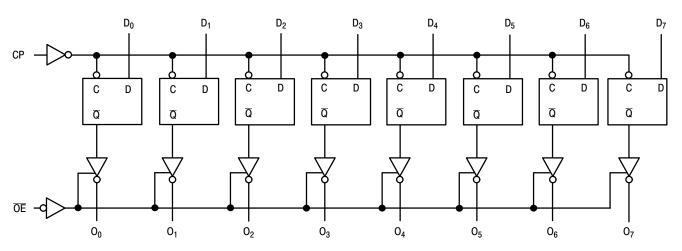
H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

Z = High Impedance

NC = No Change



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IN</sub>	DC Input Current, per Pin	±20	mA
I <sub>OUT</sub>	I <sub>OUT</sub> DC Output Sink/Source Current, per Pin		mA
I <sub>CC</sub>	I <sub>CC</sub> DC V <sub>CC</sub> or GND Current per Output Pin		mA
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V	Cupply Voltage	'AC	2.0	5.0	6.0	V
V <sub>CC</sub>	Supply Voltage	'ACT	4.5	5.0	5.5	V
V <sub>IN</sub> , V <sub>OUT</sub>	DC Input Voltage, Output Voltage (Ref. to GND)		0	=	V <sub>CC</sub>	V
		V <sub>CC</sub> @ 3.0 V	-	150	=	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 1)  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	40	=	ns/V
	7.6 Devides except estimating inputs	V <sub>CC</sub> @ 5.5 V	-	25	=	
	Input Rise and Fall Time (Note 2)	V <sub>CC</sub> @ 4.5 V	-	10	=	0 /
t <sub>r</sub> , t <sub>f</sub>	'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 5.5 V	-	8.0	=	ns/V
T <sub>A</sub>	Operating Ambient Temperature Range	-40	25	85	°C	
I <sub>OH</sub>	Output Current – High	-	-	-24	mA	
l <sub>OL</sub>	Output Current – Low		_	_	24	mA

V<sub>IN</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
 V<sub>IN</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

#### **DC CHARACTERISTICS**

			74	AC	74AC			
Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C	Unit	Conditions	
		(V)	Тур	G	uaranteed Limits			
V <sub>IH</sub>	Minimum High Level	3.0	1.5	2.1	2.1		V <sub>OUT</sub> = 0.1 V	
	Input Voltage	4.5	2.25	3.15	3.15	V	or V <sub>CC</sub> – 0.1 V	
		5.5	2.75	3.85	3.85			
V <sub>IL</sub>	Maximum Low Level	3.0	1.5	0.9	0.9		V <sub>OUT</sub> = 0.1 V	
	Input Voltage	4.5	2.25	1.35	1.35	V	or V <sub>CC</sub> – 0.1 V	
		5.5	2.75	1.65	1.65			
V <sub>OH</sub>	Minimum High Level	3.0	2.99	2.9	2.9		I <sub>OUT</sub> = -50 μA	
	Output Voltage	4.5	4.49	4.4	4.4	V		
		5.5	5.49	5.4	5.4			
							$*V_{IN} = V_{IL} \text{ or } V_{IH}$	
		3.0	_	2.56	2.46		-12 mA	
		4.5	_	3.86	3.76	V	I <sub>OH</sub> –24 mA	
		5.5	_	4.86	4.76		-24 mA	
V <sub>OL</sub>	Maximum Low Level	3.0	0.002	0.1	0.1		I <sub>OUT</sub> = 50 μA	
	Output Voltage	4.5	0.001	0.1	0.1	V		
		5.5	0.001	0.1	0.1			
							*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub>	
		3.0	_	0.36	0.44	V	12 mA	
		4.5	_	0.36	0.44	V	I <sub>OL</sub> 24 mA	
		5.5	-	0.36	0.44		24 mA	
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND	
I <sub>OLD</sub>	†Minimum Dynamic	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max	
I <sub>OHD</sub>	Output Current	5.5	_	-	-75	mA	V <sub>OHD</sub> = 3.85 V Mir	
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND	
	1		1				1	

<sup>\*</sup> All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: Note:  $I_{IN}$  and  $I_{CC}$  @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V  $V_{CC}$ .

#### AC CHARACTERISTICS (For Figures and Waveforms - See AND8277/D at www.onsemi.com)

				74AC		74	AC		
Symbol	Parameter	V <sub>CC</sub> * (V)		Γ <sub>A</sub> = +25°( C <sub>L</sub> = 50 pf		T <sub>A</sub> = -40°C C <sub>L</sub> = 5		Unit	Fig. No.
			Min	Тур	Max	Min	Max		
f <sub>max</sub>	Maximum Clock Frequency	3.3 5.0	75 95	-	- -	60 85	-	MHz	3–3
t <sub>PLH</sub>	Propagation Delay CP to O <sub>n</sub>	3.3 5.0	3.5 2.0		13.5 9.5	3.5 2.0	15 11	ns	3–6
t <sub>PHL</sub>	Propagation Delay CP to O <sub>n</sub>	3.3 5.0	3.5 2.0	-	12 8.5	3.5 2.0	13.5 9.5	ns	3–6
t <sub>PZH</sub>	Output Enable Time	3.3 5.0	2.5 2.0	-	11 8.5	2.5 2.0	12 9.0	ns	3–7
t <sub>PZL</sub>	Output Enable Time	3.3 5.0	3.0 1.5	-	10.5 8.0	3.5 2.0	11.5 9.0	ns	3–8
t <sub>PHZ</sub>	Output Disable Time	3.3 5.0	4.0 2.0	-	12 9.5	4.5 2.0	13 10.5	ns	3–7
t <sub>PLZ</sub>	Output Disable Time	3.3 5.0	2.0 1.5	- -	9.0 7.5	2.5 1.5	10 8.5	ns	3–8

<sup>\*</sup> Voltage Range 3.3 V is 3.3 V  $\pm$ 0.3 V. Voltage Range 5.0 V is 5.0 V  $\pm$ 0.5 V.

#### **AC OPERATING REQUIREMENTS**

			74AC		74AC		
Symbol	Parameter	$V_{CC}^*$ $T_A = +25^{\circ}C$ $C_L = 50 \text{ pF}$		T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF	Unit	Fig. No.	
			Тур	Gua	ranteed Minimum		
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to CP	3.3 5.0	-	2.5 1.5	3.0 2.0	ns	3–9
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP	3.3 5.0	-	1.5 1.5	1.5 1.5	ns	3–9
t <sub>w</sub>	CP Pulse Width HIGH or LOW	3.3 5.0	-	6.0 4.0	7.0 5.0	ns	3–6

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

#### **DC CHARACTERISTICS**

			74	CT	74ACT			
Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = -	+25°C	T <sub>A</sub> = -40°C to +85°C	Unit	Conditions	
		(*)	Тур	Gu	aranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V	
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V	
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	٧	I <sub>OUT</sub> = -50 μA	
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $I_{OH}$ -24 mA -24 mA	
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	٧	I <sub>OUT</sub> = 50 μA	
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $24 \text{ mA}$ $I_{OL} \qquad 24 \text{ mA}$	
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND	
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6		1.5	mA	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V	
I <sub>OZ</sub>	Maximum 3-State Current	5.5	-	±0.5	±5.0	μΑ	$\begin{aligned} &V_{I}\left(OE\right) = V_{IL}, V_{IH} \\ &V_{I} = V_{CC},  GND \\ &V_{O} = V_{CC},  GND \end{aligned}$	
I <sub>OLD</sub>	†Minimum Dynamic	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max	
I <sub>OHD</sub>	Output Current	5.5	-	-	-75	mA	V <sub>OHD</sub> = 3.85 V Mir	
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	_	8.0	80	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND	

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

### AC CHARACTERISTICS (For Figures and Waveforms - See AND8277/D at www.onsemi.com)

				74ACT		74 <b>A</b>	CT		
Symbol	Parameter	V <sub>CC</sub> * (V)			T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF		Unit	Fig. No.	
			Min	Тур	Max	Min	Max		
f <sub>max</sub>	Maximum Clock Frequency	5.0	100	-	-	85	-	ns	3–3
t <sub>PLH</sub>	Propagation Delay CP to O <sub>n</sub>	5.0	2.5	-	11	2.0	12	ns	3–6
t <sub>PHL</sub>	Propagation Delay CP to O <sub>n</sub>	5.0	2.0	-	10	1.5	11	ns	3–6
t <sub>PZH</sub>	Output Enable Time	5.0	2.0	-	9.5	1.5	10	ns	3–7
t <sub>PZL</sub>	Output Enable Time	5.0	2.0	_	9.0	1.5	10	ns	3–8
t <sub>PHZ</sub>	Output Disable Time	5.0	2.0	-	10.5	1.5	11.5	ns	3–7
t <sub>PLZ</sub>	Output Disable Time	5.0	2.0	-	8.5	1.5	9.0	ns	3–8

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V ±0.5 V.

#### **AC OPERATING REQUIREMENTS**

				74ACT	74ACT				
Symbol	Parameter	V <sub>CC</sub> * (V)							Fig. No.
			Тур	Guaran	teed Minimum				
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to CP	5.0	-	2.5	2.5	ns	3–9		
t <sub>h</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP	5.0	-	1.0	1.0	ns	3–9		
t <sub>w</sub>	CP Pulse Width HIGH or LOW	5.0	ı	3.0	4.0	ns	3–6		

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

#### **CAPACITANCE**

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	40	pF	V <sub>CC</sub> = 5.0 V

#### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
MC74AC574DWG	AC574	SOIC-20	38 Units / Rail
MC74AC574DWR2G	AC574	SOIC-20	1000 / Tape & Reel
MC74ACT574DWG	ACT574	SOIC-20	38 Units / Rail
MC74ACT574DWR2G	ACT574	SOIC-20	1000 / Tape & Reel
MC74AC574DTR2G	AC 574	TSSOP-20	2500 / Tape & Reel
MC74ACT574DTR2G	ACT 574	TSSOP-20	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

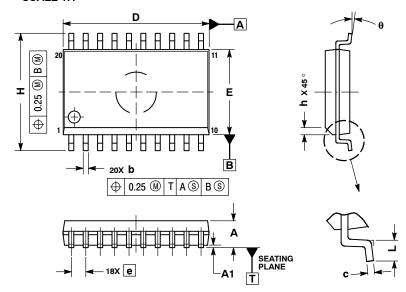




SOIC-20 WB CASE 751D-05 **ISSUE H** 

**DATE 22 APR 2015** 

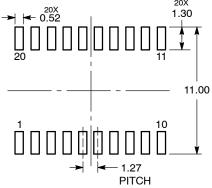
#### SCALE 1:1



- DIMENSIONS ARE IN MILLIMETERS.
   INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

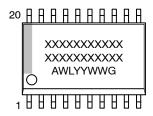
	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
b	0.35	0.49	
С	0.23	0.32	
D	12.65	12.95	
E	7.40	7.60	
е	1.27 BSC		
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
θ	0°	7 °	

#### **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

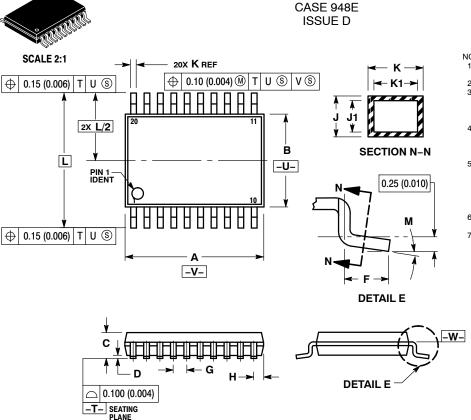
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98ASB42343B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOIC-20 WB		PAGE 1 OF 1

onsemi and ONSEMI. are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





TSSOP-20 WB

#### **DATE 17 FEB 2016**

#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

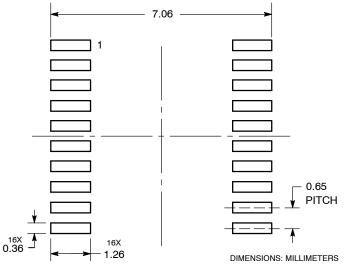
  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, OR GATE BURRS SHALL NOT
- EXCEED 0.15 (0.006) PER SIDE.

  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  DIMENSION K DOES NOT INCLUDE
- DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
  DIMENSION AT MAXIMUM MATERIAL CONDITION.
  TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
  DETERMINED AT DATUM PLANE -W-.

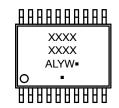
	MILLIN	IETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	BSC
М	0°	8°	0°	8°

#### **RECOMMENDED SOLDERING FOOTPRINT\***



<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location

= Wafer Lot

= Year

= Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98ASH70169A	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	TSSOP-20 WB		PAGE 1 OF 1

onsemi and ONSEMi, are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI., and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems. or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$ 

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales